

## Features

- High resistance to heat and humidity
- Resistance to mechanical shock and pressure
- Accurate dimensions for automatic surface mounting
- Wide inductance range (1.0 nH to 1000 μH)
- RoHS compliant\*

## CM45 Series SMT Chip Inductors

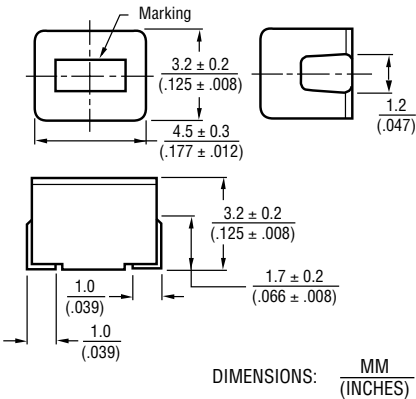
### General Specifications

Temperature Rise .....	20 °C max.
Ambient Temperature .....	100 °C max.
Operating Temperature.....	-40 °C to +125 °C
Storage Temperature.....	-40 °C to +125 °C
Resistance to Soldering Heat.....	260 °C, 5 seconds

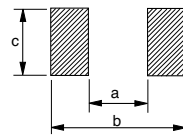
### Materials

Core Material.....	Ferrite Core
Coil Type.....	Copper wire
Enclosure.....	Epoxy resin
Terminal.....	Sn

### Product Dimensions

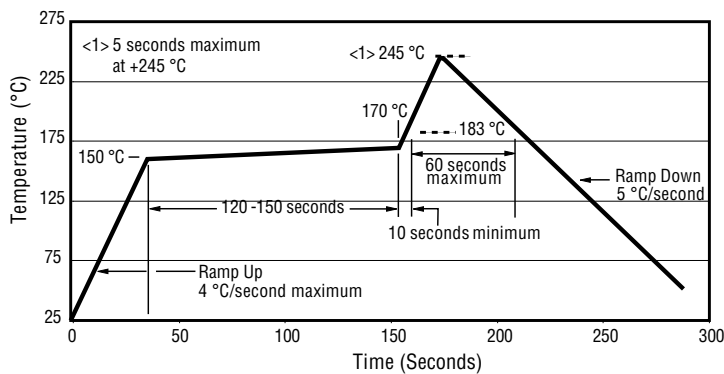


### Recommended Land Pattern Dimensions



a	b	c
$\frac{2.0 \text{ to } 2.4}{(.079 \text{ to } .094)}$	$\frac{5.0 \text{ to } 5.3}{(.197 \text{ to } .209)}$	$\frac{1.4 \text{ to } 1.7}{(.055 \text{ to } .067)}$

### Soldering Profile



\*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

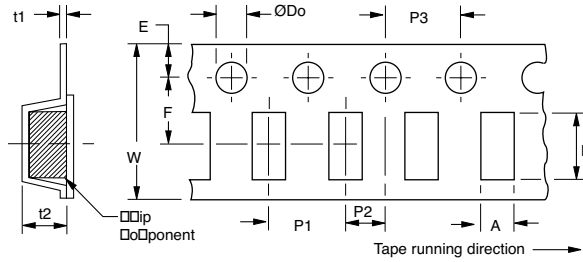
Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

# CM45 Series SMT Chip Inductors

**BOURNS®**

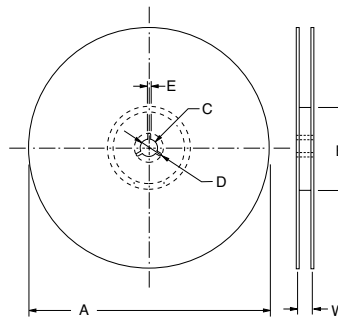
## Packaging Specifications



DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

Series	A	B	W	F	E	P1	P2	P3	D0 Dia.	D1 Dia.	t1	t2
CM45	3.60 (.142)	4.90 (.193)	12.00 (.472)	5.50 (.217)	1.75 (.069)	8.00 (.315)	2.00 (.079)	4.00 (.157)	1.50 (.059)	1.00 (.039)	0.25 (.010)	3.50 (.138)

## Reel Dimensions



DIMENSIONS:  $\frac{\text{MM}}{\text{(INCHES)}}$

A	B	C	D	E	W	Quantity	Weight
178 (7.008)	60 min.	13 (.512)	21 (.827)	2 (.079)	13 (.512)	500 pcs.	100 g

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